

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Aaron Willey	03/22/2011
Yantao Ma	08/01/2011
RECEIVING PARTY DATA	
Name:	NANYA TECHNOLOGY CORP.
Street Address:	Hwa-Ya Technology Park 669, Fuhsing 3 Rd., Kueishan
City:	Tao-Yuan Hsien
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13208349
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	JANINE CHANG
Total Attachments: 4 source=1180470#page1.tif source=1180470#page2.tif source=1180470#page3.tif source=1180470#page4.tif	

CH \$40.00 13208349

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PATENT
REEL: 026738 FRAME: 0927

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Aaron Willey Nationality: US

Name: Yantao Ma Nationality: US

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: NANYA TECHNOLOGY CORP.

Address: Hwa-Ya Technology Park 669, Fuhsing 3 Rd., Kucishan, Tao-Yuan Hsien, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"SEMICONDUCTOR PACKAGE STRUCTURE WITH LOW INDUCTANCE"

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____
(e) _____ International application no. _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 3/22/2011 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Aaron Willey



Yantao Ma

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(Type name of inventor)

Signature of INVENTOR

Aaron Willey

Yantao Ma

 8/11/11